

What is claimed is

5 1. A circuit module comprising:

A carrier;

10 stacks of circuit chips arranged on a surface of the carrier
and including several circuit chips arranged in different
layers,

wherein the circuit chips are grouped in different groups,
wherein the groups are not active at the same time,

15 wherein the circuit chips are arranged such that circuit
chips belonging to the same group are arranged in different
layers in adjacent stacks.

20 2. Circuit module according to claim 1, wherein stacks of
circuit chips are arranged on a first surface and a second
surface of the carrier.

25 3. Circuit module according to claim 1, wherein the circuit
module is a memory module and the circuit chips are memory
chips.

30 4. Circuit module according to claim 3, wherein the memory
module is a DIMM and the memory chips are DRAMs.

5. Circuit module according to claim 3, wherein the groups
into which the circuit chips are grouped are respective
memory banks.

35 6. Circuit module according to claim 1, further comprising
means to activate the circuit chips belonging to the same
group.

7. Circuit module according to claim 6, wherein the means to activate the circuit chips belonging to the same group comprises a bank select signal.